

## AP2222D 20V N-Channel Enhancement Mode MOSFET

#### Description

The AP2222D uses advanced trench technology

to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This

device is suitable for use as a Battery protection

or in other Switching application.

#### **General Features**

VDS=20V ID=50A

 $R_{\text{DS(ON)}} < 10.5 \text{m}\Omega ~ @ \text{V}_{\text{GS}} = 4.5 \text{V} \quad (\text{Type: } 8.5 \text{m}\Omega)$ 

#### Application

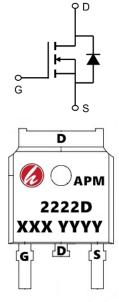
Battery protection

Load switch

Uninterruptible power supply

#### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)			
AP2222D	TO-252-3L	AP2222D XXX YYYY	2500			
Absolute Maximur	Absolute Maximum Ratings (TC=25℃unless otherwise noted)					
Symbol	Parameter	Max.	Units			
VDSS	Drain-Source Voltage	20	V			
VGSS	Gate-Source Voltage	±12	V			
ID@TA=25℃	Continuous Drain Current, VGS @ 4.5V	50	А			
ID@TA=70℃	Continuous Drain Current, VGS @ 4.5V	20	А			
IDM	Pulsed Drain Current note1	120	А			
EAS	Single Pulsed Avalanche Energy note2	Single Pulsed Avalanche Energy note2 23				
PD@TA=25℃	Power Dissipation	20				
RθJC	Thermal Resistance, Junction to Case	7.5 °C/W				
TJ, TSTG	Operating and Storage Temperature Range	-55 to +150	°C			





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### Electrical Characteristics (Tc=25°C, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	20	24	-	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	0.5	0.75	1.2	V
RDS(on)	Static Drain-Source on-Resistance note3	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	-	8.5	10.5	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =10A	-	11.7	17.5	
C <sub>iss</sub>	Input Capacitance		-	1000	1500-	pF
Coss	Output Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1.0MHz	-	182	-	pF
Crss	Reverse Transfer Capacitance		-	164	-	pF
Qg	Total Gate Charge		-	15	-	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =10V, I <sub>D</sub> =15A, V <sub>GS</sub> =4.5V	-	2	-	nC
$Q_gd$	Gate-Drain("Miller") Charge	VGS=4.5V	-	5.2	-	nC
td(on)	Turn-on Delay Time	N/ 40V/	-	9	-	ns
tr	Turn-on Rise Time	V <sub>DS</sub> =10V,	-	25	-	ns
td(off)	Turn-off Delay Time	I <sub>D</sub> =15A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =4.5V	-	37	-	ns
t <sub>f</sub>	Turn-off Fall Time	VGS=4.5V	-	14	-	ns
IS	Maximum Continuous Drain to Source Diode ForwardCurrent		-	-	30	А
ISM	Maximum Pulsed Drain to Source Diode Forward Current		-	-	120	А
VSD	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	1.2	V

#### Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

 $2\,{\scriptstyle \sim}\,$  The test condition is, VDD=10V, VG=4.5V, L=0.5mH, RG=25\Omega, IAS=9.6A

3、 The data tested by pulsed Pulse Test: Pulse Width $\leq$ 300µs, Duty Cycle $\leq$ 0.5%

 $4_{\scriptscriptstyle N}$  The power dissipation is limited by 150  $^\circ\!\!\mathbb{C}$  junction temperature

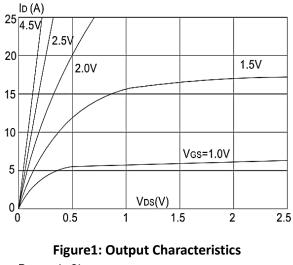
N

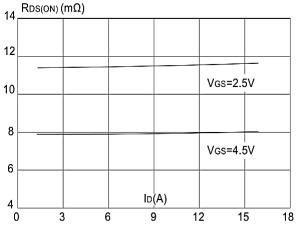


# AP2222D

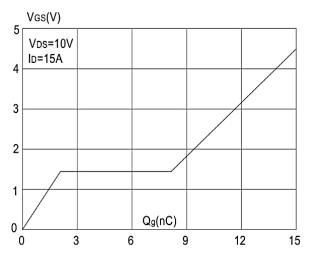
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### **Typical Characteristics**

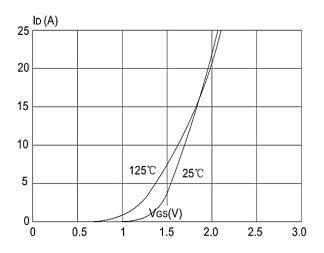




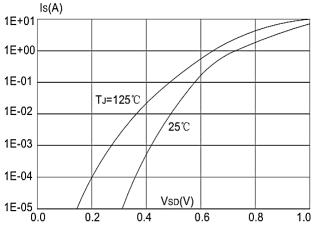
#### Figure 3:On-resistance vs. Drain Current



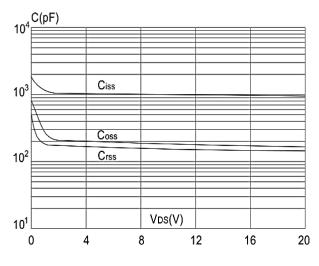
**Figure 5: Gate Charge Characteristics** 







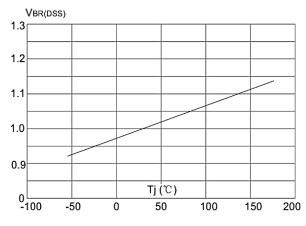




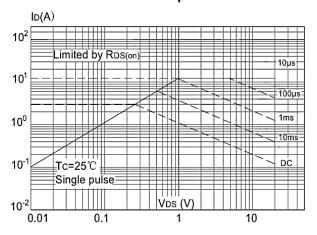
**Figure 6: Capacitance Characteristics** 



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### Figure 7: Normalized Breakdown Voltage vs. Junction Temperature





Current



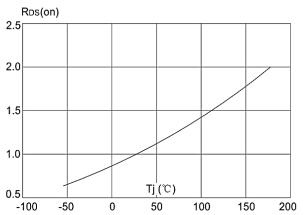


Figure 8: Normalized on Resistance vs Junction Temperature

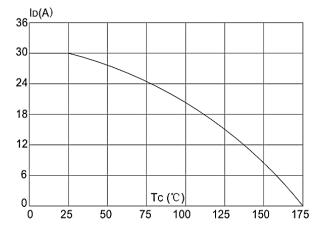
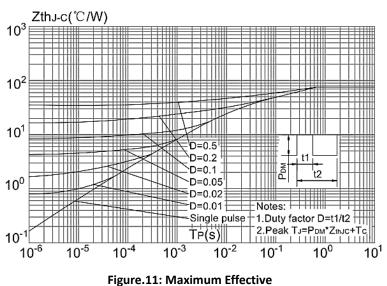


Figure 10: Maximum Continuous Drain

vs. Case



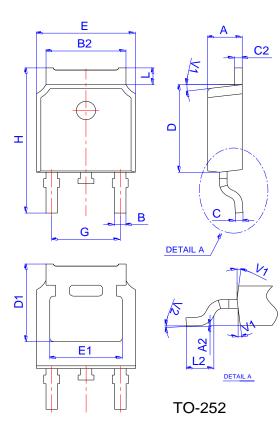
Transient Thermal Impedance, Junction-to-Case

4



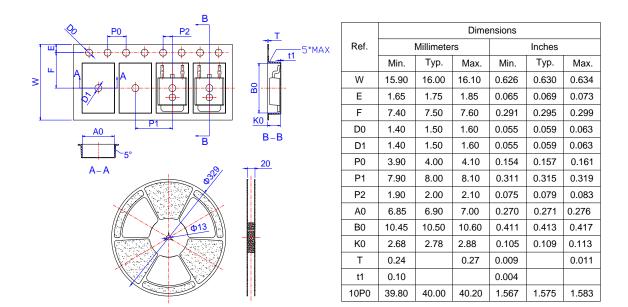
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## Package Mechanical Data:TO-252-3L



	Dimensions					
Ref.	Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	:	5.30REF		0	.209REF	-
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

### **Reel Spectification-TO-252**



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AP2222D RVE1.0



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## 20V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2018/8/31	Initial release

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